

**AMENDMENTS TO THE CLAIMS**

Listing of the claims:

Following is a listing of all claims in the present application, which listing supersedes all previously presented claims:

1. (Cancelled)

2. (Cancelled)

3. (Withdrawn)      A method of cleaning a component for a film forming equipment, characterized by that after a thin film has been formed on the substrate by the film forming equipment, the component as claimed in claim 1 or 2 is dipped in a cleaning fluid to remove an deposited film consisting of the film forming material from the component.

4. (Withdrawn)      The method as claimed in claim 3, characterized by that a positive electric field is applied to the matrix metal material of said component dipped in the cleaning fluid.

5. (Cancelled)

6. (Previously Presented)      A component in a film forming equipment for forming a thin film on a substrate, the component having:  
  
a matrix material;

a first means on said matrix material for forming a first local cell, when exposed to a cleaning liquid, with the matrix material so that a first local current flows from the matrix material thereby advancing dissolution of the first means at an interface between the first means and the matrix material and allowing the removal of a film layer of the thin film from the matrix material; and

a second means on said first means forming a second local cell, when exposed to a cleaning liquid, so that a second local current flows from the second means thereby advancing dissolution of the first means at an interface between the first means and the second means and allowing the removal of the film layer of the thin film from the matrix material.